SCLS191B - FEBRUARY 1993 - REVISED APRIL 1996

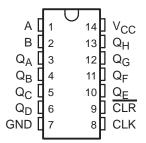
- EPIC™ (Enhanced-Performance Implanted CMOS) 2-µ Process
- Typical V_{OLP} (Output Ground Bounce)
 < 0.8 V at V_{CC}, T_A = 25°C
- Typical V_{OHV} (Output V_{OH} Undershoot)
 > 2 V at V_{CC}, T_A = 25°C
- ESD Protection Exceeds 2000 V Per MIL-STD-883C, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 250 mA Per JEDEC Standard JESD-17
- Package Options Include Plastic Small-Outline (D), Shrink Small-Outline (DB), Thin Shrink Small-Outline (PW), Ceramic Flat (W) Packages, Chip Carriers (FK), and (J) 300-mil DIPs

description

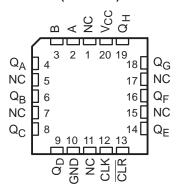
These 8-bit parallel-out serial shift registers are designed for 2.7-V to 5.5-V V_{CC} operation.

The 'LV164 feature AND-gated serial (A and B) inputs and an asynchronous clear (CLR) input. The gated serial inputs permit complete control over incoming data as a low at either input inhibits entry of the new data and resets the first flip-flop to the low level at the next clock pulse. A high-level

SN54LV164 . . . J OR W PACKAGE SN74LV164 . . . D, DB, OR PW PACKAGE (TOP VIEW)



SN54LV164 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

input enables the other input, which then determines the state of the first flip-flop. Data at the serial inputs can be changed while the clock is high or low, provided the minimum setup time requirements are met. Clocking occurs on the low-to-high-level transition of the clock (CLK) input.

The SN74LV164 is available in TI's shrink small-outline package (DB), which provides the same I/O pin count and functionality of standard small-outline packages in less than half the printed-circuit-board area.

The SN54LV164 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74LV164 is characterized for operation from –40°C to 85°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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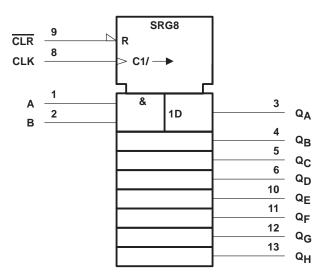
FUNCTION TABLE

	INPU	JTS	OUTPUTS					
CLR	CLK	Α	В	Q_{A}	Q _B .	QH		
L	Х	Χ	Χ	L	L	L		
Н	L	Χ	X	Q_{A0}	Q_{B0}	Q_{H0}		
Н	\uparrow	Н	Н	Н	Q_{An}	Q_Gn		
Н	\uparrow	L	X	L	Q_{An}	Q_{Gn}		
Н	\uparrow	Χ	L	L	Q_{An}	Q_{Gn}		

 ${\rm Q}_{A0},\,{\rm Q}_{B0},\,{\rm Q}_{H0}$ = the level of ${\rm Q}_A,\,{\rm Q}_B,$ or ${\rm Q}_H,$ respectively, before the indicated steady-state inputs conditions were established

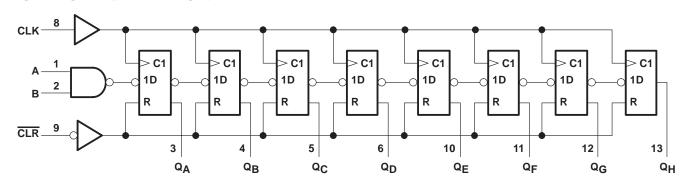
 Q_{An} , Q_{Gn} = the level of Q_A or Q_G before the most recent \uparrow transition of the clock: indicates a 1-bit shift

logic symbol†

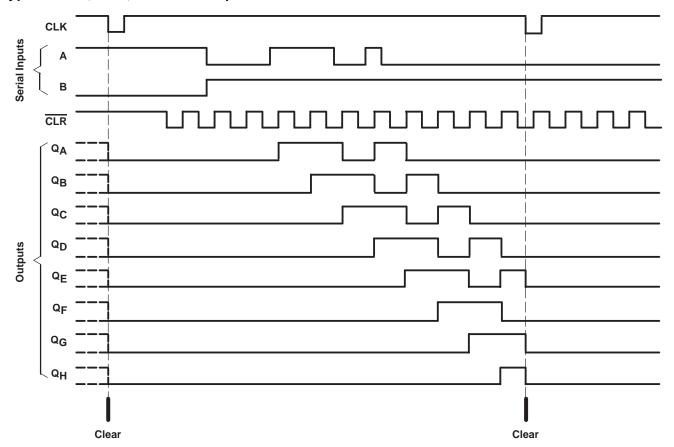


[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for D, DB, J, PW, and W packages.

logic diagram (positive logic)



typical clear, shift, and clear sequences



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	0.5 V to 7	٧
Input voltage range, V _I (see Note 1)		٧
Output voltage range, VO (see Notes 1 and 2)		V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$)	±20 m	Α
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$)	±50 m	Α
Continuous output current, $I_O(V_O = 0 \text{ to } V_{CC})$	±25 m	Α
Continuous current through V _{CC} or GND	±50 m	Α
Maximum power dissipation at $T_A = 55^{\circ}C$ (in still air) (see Note 3):) package1.25 \	N
	DB or PW package 0.5 \	N
Storage temperature range, T _{sto}		

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

- 2. This value is limited to 7 V maximum.
- 3. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils.



SN54LV164, SN74LV164 8-BIT PARALLEL-OUT SERIAL SHIFT REGISTERS

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recommended operating conditions (see Note 4)

			SN54L	V164	SN74L	.V164	
			MIN	MAX	MIN	MAX	UNIT
Vcc	Supply voltage		2.7	5.5	2.7	5.5	V
\/	High level input valtage	$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	2		2		V
VIH	High-level input voltage	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	3.15		3.15		V
.,	Level Level Considerable and	$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$		0.8		0.8	V
VIL	Low-level input voltage	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		1.65		1.65	V
٧ _I	Input voltage		0	Vcc	0	VCC	V
VO	Output voltage		0	VCC	0	VCC	V
	I Park Level and and an extra set	$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	20	-6		-6	4
ЮН	High-level output current	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	100	-12		-12	mA
		V _{CC} = 2.7 V to 3.6 V	V	6		6	
lOL	Low-level output current	V _{CC} = 4.5 V to 5.5 V		12		12	mA
Δt/Δν	Input transition rise or fall rate		0	100	0	100	ns/V
T _A	Operating free-air temperature		-55	125	-40	85	°C

NOTE 4: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETER	TEST COMPITIONS	V +	SN	54LV16	4	SN	74LV16	4	UNIT
PARAMETER	TEST CONDITIONS	v _{cc} †	MIN	TYP	MAX	MIN	TYP	MAX	UNII
	I _{OH} = -100 μA	MIN to MAX	V _{CC} - 0	.2		VCC - 0	.2		
VOH	$I_{OH} = -6 \text{ mA}$	3 V	2.4			2.4			V
	$I_{OH} = -12 \text{ mA}$	4.5 V	3.6			3.6			
	I _{OL} = 100 μA	MIN to MAX			0.2			0.2	
VOL	I _{OL} = 6 mA	3 V		19	0.4			0.4	V
	$I_{OL} = 12 \text{ mA}$			EL	0.55			0.55	
1.	W. W on CND	3.6 V		2	±1			±1	^
IĮ	$V_I = V_{CC}$ or GND	5.5 V		Ć,	±1			±1	μΑ
1	W. Was an CNID	3.6 V	9		20			20	^
Icc	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V	Q.		20			20	μΑ
ΔICC	One input at V _{CC} – 0.6 V, Other inputs at V _{CC} or GND	3 V to 3.6 V			500			500	μА
0	V. V or CND	3.3 V	2.5		2.5 2.5				
Ci	V _I = V _{CC} or GND	5 V		3			3		pF

[†] For conditions shown as MIN or MAX, use the appropriate values under recommended operating conditions.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

					SI	N54LV16	64		
			V _{CC} =		V _{CC} =		V _{CC} =	2.7 V	UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
fclock	Clock frequency		0	40	0	35	0	30	MHz
	Podes doneties	CLR low	14		16		18		
t _W	Pulse duration	CLK high or low	14	ODI	16	~	18		ns
	Satura tima a data hafara CLIVA	Data	8	PRO	10	PRO	12		
t _{su}	Setup time, data before CLK↑	CLR inactive	5	64	6	<	7		ns
th	Hold time, data after CLK↑		3		3		3		ns

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

				SI	N74LV16	64		_	
			V _{CC} =		V _{CC} =		V _{CC} =	2.7 V	UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
fclock	Clock frequency		0	40	0	35	0	30	MHz
	Dulas deserva	CLR low	14		16		18		
t _W	Pulse duration	CLK high or low	14		16		18		ns
	Cation time data before CLIVA	Data	8		10		12		
t _{su}	Setup time, data before CLK↑	CLR inactive	5		6		7		ns
t _h	Hold time, data after CLK↑	_	3		3		3		ns

switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

						SN54L	V164				
PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 5.5 V \pm 0.5 V$		V_{CC} = 3.3 V \pm 0.3 V			V _{CC} = 2.7 V		UNIT	
	(INFOT)		MIN	TYP	MAX	MIN	TYP	MAX	∴ MIN	MAX	
f _{max}			40	90	الم	35	75	apu	30		MHz
^t pd	CLK	Q		10	20	ZII.	14	26	7:	32	ns
^t PHL	CLR	Q		12	20		16	26		32	ns

switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

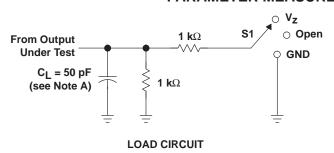
			SN74LV164								
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 5.5 V \pm 0.5 V		V_{CC} = 3.3 V \pm 0.3 V			$V_{CC} = 2.7 \text{ V}$		UNIT	
(IIV	(1141 01)	(0011 01)	MIN	TYP	MAX	MIN	TYP	MAX	MIN	MAX	
f _{max}			40	90		35	75		30		MHz
^t pd	CLK	Q		10	20		14	26		32	ns
^t PHL	CLR	Q		12	20		16	26		32	ns

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operating characteristics, $T_A = 25^{\circ}C$

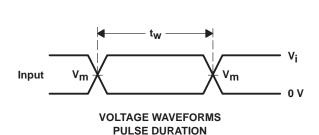
	PARAMETER	TEST CONDITIONS	TYP	TYP	UNIT
C	Down discination conscitons	C. FO. F. 4 40 MILE	3.3 V	74	, r
Cpd	Power dissipation capacitance	$C_L = 50 \text{ pF}, f = 10 \text{ MHz}$	5 V	75	pF

PARAMETER MEASUREMENT INFORMATION



TEST	S1
tPLH/tPH	= i.
tPHZ/tPZ	H GND

WAVEFORM CONDITION	V _{CC} = 4.5 V to 5.5 V	V _{CC} = 2.7 V to 3.6 V
٧ _m	0.5 × V _{CC}	1.5 V
Vi	VCC	2.7 V
Vz	2×V _{CC}	6 V



Timing Input

V_m

0 V

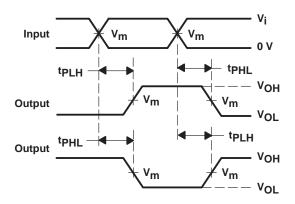
V_m

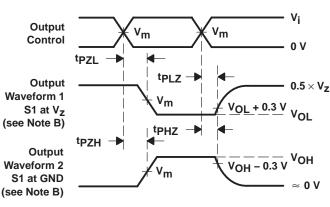
V_m

V_m

0 V

VOLTAGE WAVEFORMS SETUP AND HOLD TIMES





VOLTAGE WAVEFORMS PROPAGATION DELAY TIMES INVERTING AND NONINVERTING OUTPUTS

VOLTAGE WAVEFORMS ENABLE AND DISABLE TIMES LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$, $t_f \leq 2.5$ ns, $t_f \leq 2.5$ ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms







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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74LV164D	OBSOLETE	SOIC	D	14	TBD	Call TI	Call TI
SN74LV164DR	OBSOLETE	SOIC	D	14	TBD	Call TI	Call TI
SN74LV164PWLE	OBSOLETE	TSSOP	PW	14	TBD	Call TI	Call TI

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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